

Title (en)
ADHESIVE COMPOSITIONS THAT ARE REMOVABLE AFTER THERMOSETTING

Title (de)
NACH HITZEHÄRTUNG ABNEHMBARE KLEBSTOFFZUSAMMENSETZUNGEN

Title (fr)
COMPOSITIONS ADHESIVES ENLEVABLES APRES THERMODURCISSEMENT

Publication
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Application
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Priority
US 9707505 W 19970505

Abstract (en)
[origin: WO9850480A1] Thermosettable adhesive compositions that include a polyepoxide resin, a curing agent, and a plurality of microspheres. The microspheres, polyepoxide resin, and curing agent and the relative amounts thereof, are selected such that upon cure the composition is capable of forming a semi-structural bond to a substrate and is cleanly thermally removable from the substrate.

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IPC 8 full level
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